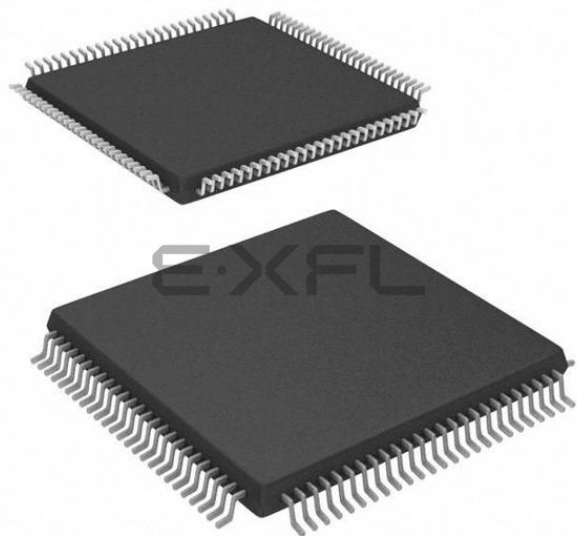




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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	576
Number of Logic Elements/Cells	1368
Total RAM Bits	18432
Number of I/O	77
Number of Gates	30000
Voltage - Supply	4.75V ~ 5.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	100-TQFP
Supplier Device Package	100-VQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcs30-4vq100c

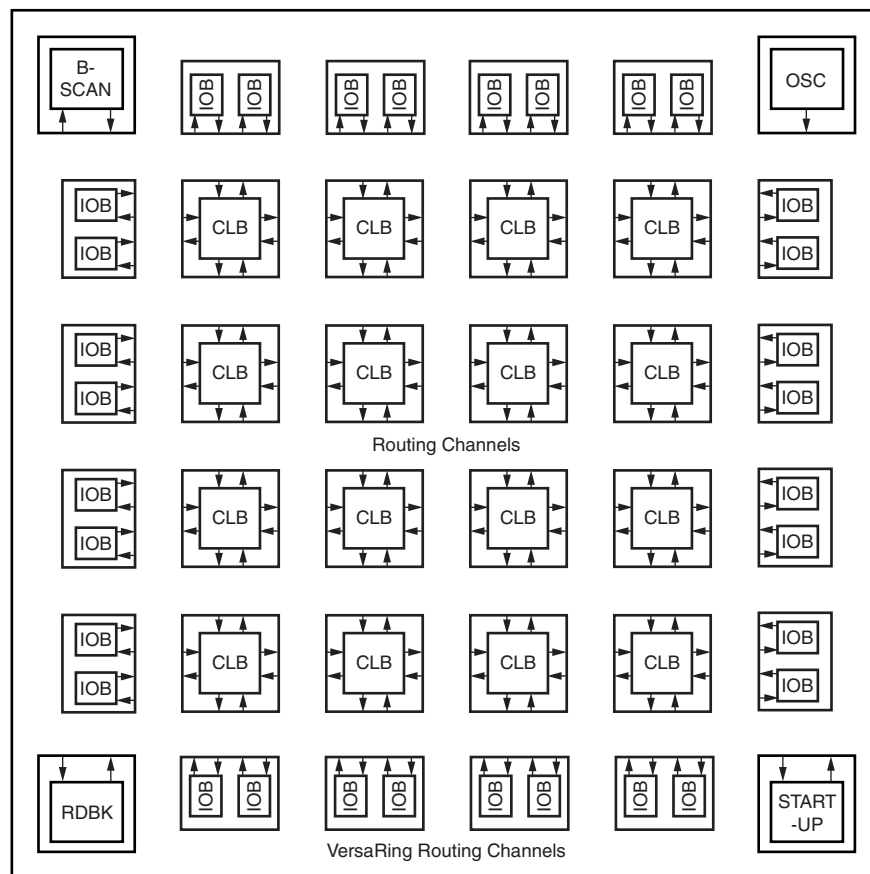
General Overview

Spartan series FPGAs are implemented with a regular, flexible, programmable architecture of Configurable Logic Blocks (CLBs), interconnected by a powerful hierarchy of versatile routing resources (routing channels), and surrounded by a perimeter of programmable Input/Output Blocks (IOBs), as seen in **Figure 1**. They have generous routing resources to accommodate the most complex interconnect patterns.

The devices are customized by loading configuration data into internal static memory cells. Re-programming is possible an unlimited number of times. The values stored in these

memory cells determine the logic functions and interconnections implemented in the FPGA. The FPGA can either actively read its configuration data from an external serial PROM (Master Serial mode), or the configuration data can be written into the FPGA from an external device (Slave Serial mode).

Spartan series FPGAs can be used where hardware must be adapted to different user applications. FPGAs are ideal for shortening design and development cycles, and also offer a cost-effective solution for production rates well beyond 50,000 systems per month.



DS060_01_081100

Figure 1: Basic FPGA Block Diagram

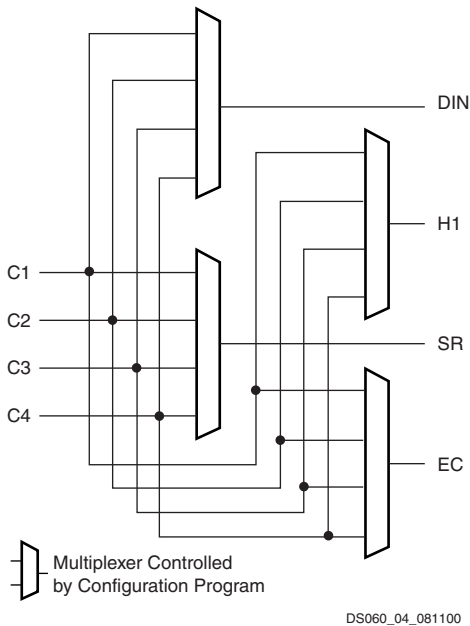


Figure 4: CLB Control Signal Interface

The four internal control signals are:

- EC: Enable Clock
- SR: Asynchronous Set/Reset or H function generator Input 0
- DIN: Direct In or H function generator Input 2
- H1: H function generator Input 1.

Input/Output Blocks (IOBs)

User-configurable input/output blocks (IOBs) provide the interface between external package pins and the internal logic. Each IOB controls one package pin and can be configured for input, output, or bidirectional signals. Figure 6 shows a simplified functional block diagram of the Spartan/XL FPGA IOB.

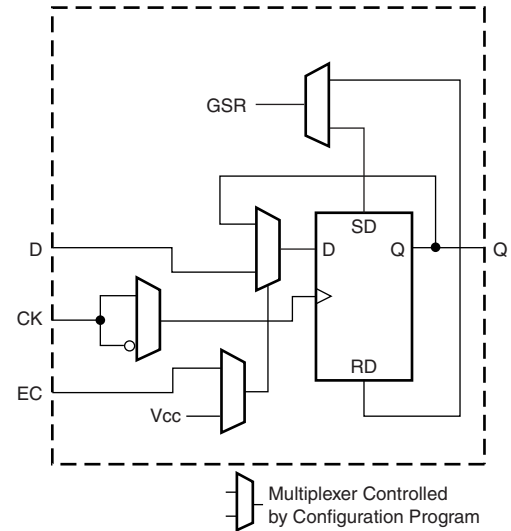


Figure 5: IOB Flip-Flop/Latch Functional Block Diagram

IOB Input Signal Path

The input signal to the IOB can be configured to either go directly to the routing channels (via I1 and I2 in Figure 6) or to the input register. The input register can be programmed as either an edge-triggered flip-flop or a level-sensitive latch. The functionality of this register is shown in Table 3, and a simplified block diagram of the register can be seen in Figure 5.

Table 3: Input Register Functionality

Mode	CK	EC	D	Q
Power-Up or GSR	X	X	X	SR
Flip-Flop		1*	D	D
	0	X	X	Q
Latch	1	1*	X	Q
	0	1*	D	D
Both	X	0	X	Q

Legend:

- X Don't care.
- Rising edge (clock not inverted).
- SR Set or Reset value. Reset is default.
- 0* Input is Low or unconnected (default value)
- 1* Input is High or unconnected (default value)

The register choice is made by placing the appropriate library symbol. For example, IFD is the basic input flip-flop (rising edge triggered), and ILD is the basic input latch (transparent-High). Variations with inverted clocks are also available. The clock signal inverter is also shown in Figure 5 on the CK line.

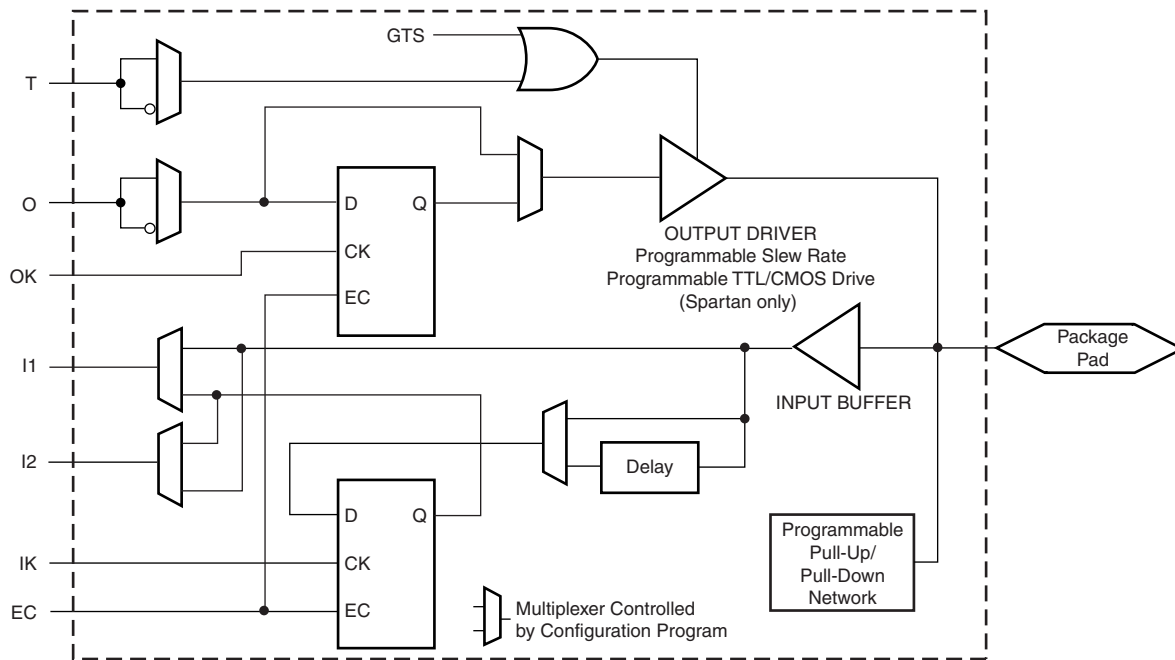
The Spartan family IOB data input path has a one-tap delay element: either the delay is inserted (default), or it is not. The Spartan-XL family IOB data input path has a two-tap delay element, with choices of a full delay, a partial delay, or no delay. The added delay guarantees a zero hold time with respect to clocks routed through the global clock buffers. (See **Global Nets and Buffers**, page 12 for a description of the global clock buffers in the Spartan/XL families.) For a shorter input register setup time, with positive hold-time, attach a NODELAY attribute or property to the flip-flop. The output of the input register goes to the routing channels (via I1 and I2 in Figure 6). The I1 and I2 signals that exit the IOB can each carry either the direct or registered input signal.

The 5V Spartan family input buffers can be globally configured for either TTL (1.2V) or CMOS (VCC/2) thresholds,

using an option in the bitstream generation software. The Spartan family output levels are also configurable; the two global adjustments of input threshold and output level are independent. The inputs of Spartan devices can be driven by the outputs of any 3.3V device, if the Spartan family inputs are in TTL mode. Input and output thresholds are TTL on all configuration pins until the configuration has been loaded into the device and specifies how they are to be used. Spartan-XL family inputs are TTL compatible and 3.3V CMOS compatible.

Supported sources for Spartan/XL device inputs are shown in Table 4.

Spartan-XL family I/Os are fully 5V tolerant even though the V_{CC} is 3.3V. This allows 5V signals to directly connect to the Spartan-XL family inputs without damage, as shown in Table 4. In addition, the 3.3V V_{CC} can be applied before or after 5V signals are applied to the I/Os. This makes the Spartan-XL devices immune to power supply sequencing problems.



DS060_06_041901

Figure 6: Simplified Spartan/XL IOB Block Diagram

- The 16 x 1 single-port configuration contains a RAM array with 16 locations, each one-bit wide. One 4-bit address decoder determines the RAM location for write and read operations. There is one input for writing data and one output for reading data, all at the selected address.
- The (16 x 1) x 2 single-port configuration combines two 16 x 1 single-port configurations (each according to the preceding description). There is one data input, one data output and one address decoder for each array. These arrays can be addressed independently.
- The 32 x 1 single-port configuration contains a RAM array with 32 locations, each one-bit wide. There is one data input, one data output, and one 5-bit address decoder.
- The dual-port mode 16 x 1 configuration contains a RAM array with 16 locations, each one-bit wide. There are two 4-bit address decoders, one for each port. One port consists of an input for writing and an output for reading, all at a selected address. The other port consists of one output for reading from an independently selected address.

The appropriate choice of RAM configuration mode for a given design should be based on timing and resource requirements, desired functionality, and the simplicity of the design process. Selection criteria include the following: Whereas the 32 x 1 single-port, the (16 x 1) x 2 single-port, and the 16 x 1 dual-port configurations each use one entire CLB, the 16 x 1 single-port configuration uses only one half of a CLB. Due to its simultaneous read/write capability, the dual-port RAM can transfer twice as much data as the single-port RAM, which permits only one data operation at any given time.

CLB memory configuration options are selected by using the appropriate library symbol in the design entry.

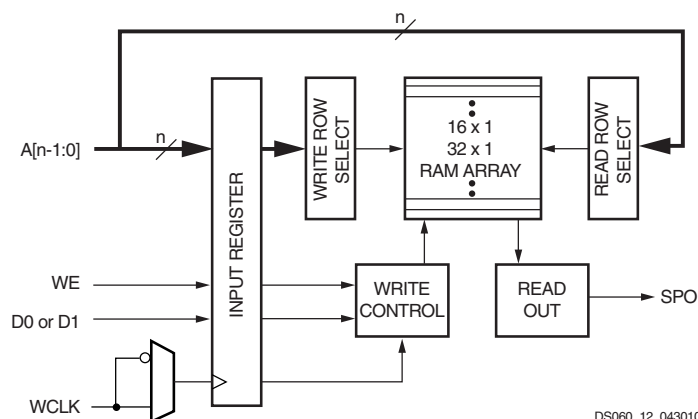
Single-Port Mode

There are three CLB memory configurations for the single-port RAM: 16 x 1, (16 x 1) x 2, and 32 x 1, the functional organization of which is shown in [Figure 12](#).

The single-port RAM signals and the CLB signals ([Figure 2](#), [page 4](#)) from which they are originally derived are shown in [Table 9](#).

Table 9: Single-Port RAM Signals

RAM Signal	Function	CLB Signal
D0 or D1	Data In	DIN or H1
A[3:0]	Address	F[4:1] or G[4:1]
A4 (32 x 1 only)	Address	H1
WE	Write Enable	SR
WCLK	Clock	K
SPO	Single Port Out (Data Out)	F _{OUT} or G _{OUT}



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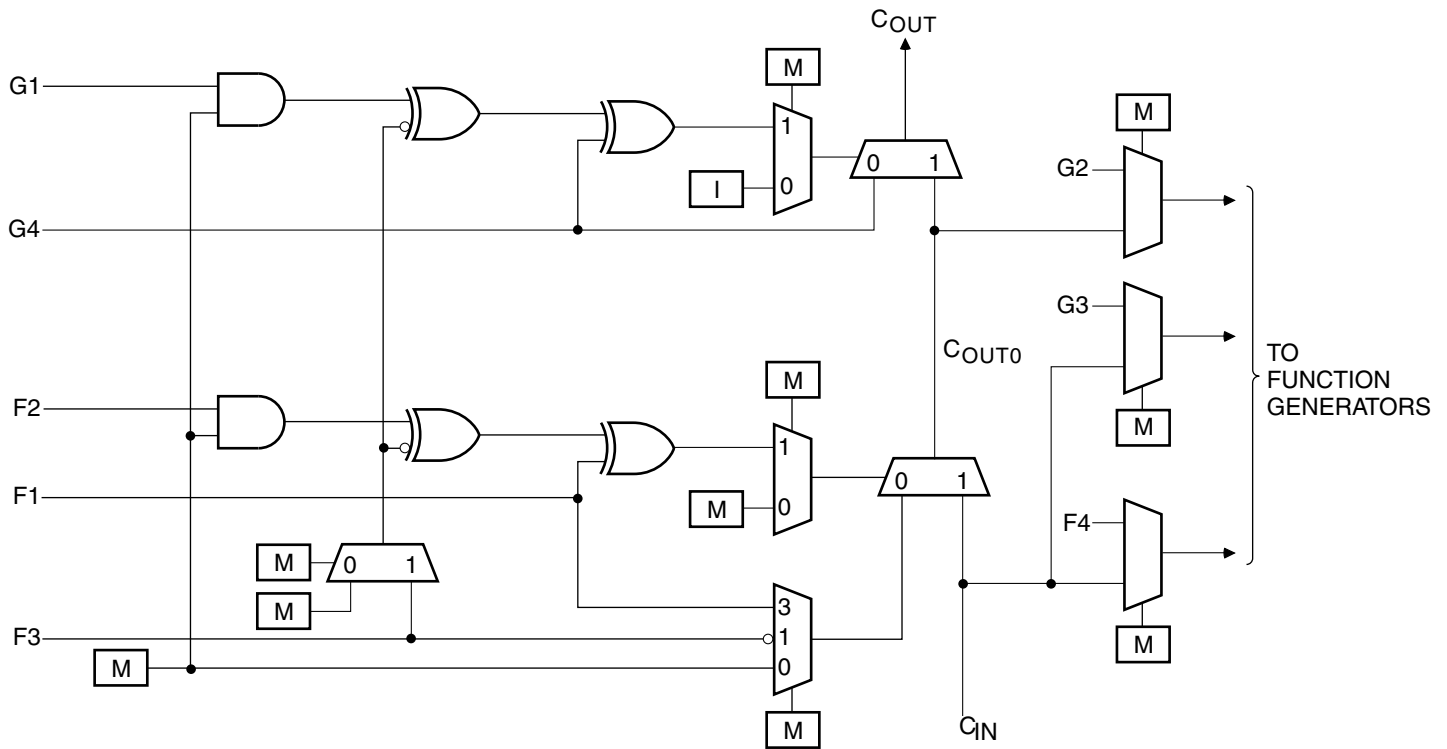
Notes:

1. The (16 x 1) x 2 configuration combines two 16 x 1 single-port RAMs, each with its own independent address bus and data input. The same WE and WCLK signals are connected to both RAMs.
2. $n = 4$ for the 16 x 1 and (16 x 1) x 2 configurations. $n = 5$ for the 32 x 1 configuration.

Figure 12: Logic Diagram for the Single-Port RAM

Writing data to the single-port RAM is essentially the same as writing to a data register. It is an edge-triggered (synchronous) operation performed by applying an address to the A inputs and data to the D input during the active edge of WCLK while WE is High.

The timing relationships are shown in [Figure 13](#). The High logic level on WE enables the input data register for writing. The active edge of WCLK latches the address, input data, and WE signals. Then, an internal write pulse is generated that loads the data into the memory cell.



DS060_17_080400

Figure 17: Detail of Spartan/XL Dedicated Carry Logic

3-State Long Line Drivers

A pair of 3-state buffers is associated with each CLB in the array. These 3-state buffers (BUFT) can be used to drive signals onto the nearest horizontal longlines above and below the CLB. They can therefore be used to implement multiplexed or bidirectional buses on the horizontal longlines, saving logic resources.

There is a weak keeper at each end of these two horizontal longlines. This circuit prevents undefined floating levels. However, it is overridden by any driver.

The buffer enable is an active High 3-state (i.e., an active Low enable), as shown in Table 11.

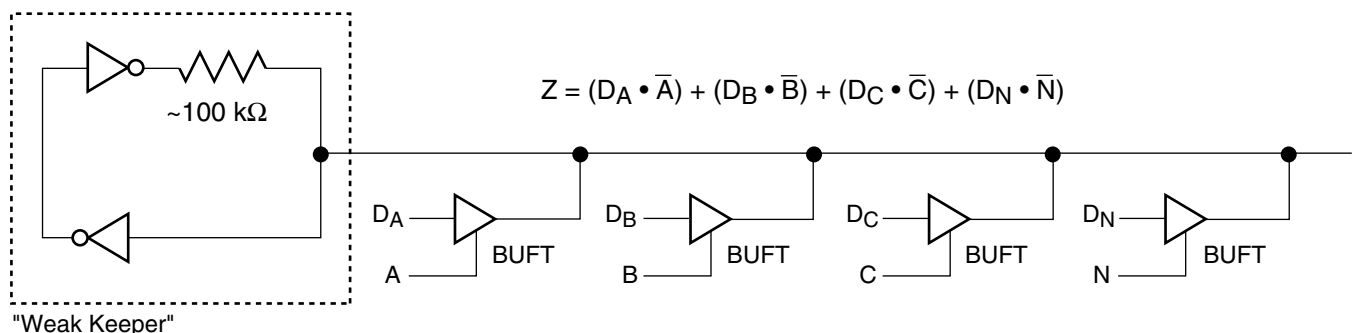
Three-State Buffer Example

Figure 18 shows how to use the 3-state buffers to implement a multiplexer. The selection is accomplished by the buffer 3-state signal.

Pay particular attention to the polarity of the T pin when using these buffers in a design. Active High 3-state (T) is identical to an active Low output enable, as shown in Table 11.

Table 11: Three-State Buffer Functionality

IN	T	OUT
X	1	Z
IN	0	IN



DS060_18_080400

Figure 18: 3-state Buffers Implement a Multiplexer

Figure 20 is a diagram of the Spartan/XL FPGA boundary scan logic. It includes three bits of Data Register per IOB, the IEEE 1149.1 Test Access Port controller, and the Instruction Register with decodes.

Spartan/XL devices can also be configured through the boundary scan logic. See **Configuration Through the Boundary Scan Pins**, page 37.

Data Registers

The primary data register is the boundary scan register. For each IOB pin in the FPGA, bonded or not, it includes three bits for In, Out and 3-state Control. Non-IOB pins have appropriate partial bit population for In or Out only. PROGRAM, CCLK and DONE are not included in the boundary scan register. Each EXTEST CAPTURE-DR state captures all In, Out, and 3-state pins.

The data register also includes the following non-pin bits: TDO.T, and TDO.O, which are always bits 0 and 1 of the data register, respectively, and BSCANT.UPD, which is always the last bit of the data register. These three boundary scan bits are special-purpose Xilinx test signals.

The other standard data register is the single flip-flop BYPASS register. It synchronizes data being passed through the FPGA to the next downstream boundary scan device.

The FPGA provides two additional data registers that can be specified using the BSCAN macro. The FPGA provides two user pins (BSCAN.SEL1 and BSCAN.SEL2) which are the decodes of two user instructions. For these instructions, two corresponding pins (BSCAN.TDO1 and BSCAN.TDO2) allow user scan data to be shifted out on TDO. The data register clock (BSCAN.DRCK) is available for control of test logic which the user may wish to implement with CLBs. The NAND of TCK and RUN-TEST-IDLE is also provided (BSCAN.IDLE).

Instruction Set

The Spartan/XL FPGA boundary scan instruction set also includes instructions to configure the device and read back the configuration data. The instruction set is coded as shown in Table 12.

Spartan Family Detailed Specifications

Definition of Terms

In the following tables, some specifications may be designated as Advance or Preliminary. These terms are defined as follows:

Advance: Initial estimates based on simulation and/or extrapolation from other speed grades, devices, or families. Values are subject to change. Use as estimates, not for production.

Preliminary: Based on preliminary characterization. Further changes are not expected.

Unmarked: Specifications not identified as either Advance or Preliminary are to be considered Final.

Notwithstanding the definition of the above terms, all specifications are subject to change without notice.

Except for pin-to-pin input and output parameters, the AC parameter delay specifications included in this document are derived from measuring internal test patterns. All specifications are representative of worst-case supply voltage and junction temperature conditions. The parameters included are common to popular designs and typical applications.

Spartan Family Absolute Maximum Ratings⁽¹⁾

Symbol	Description		Value	Units
V_{CC}	Supply voltage relative to GND		-0.5 to +7.0	V
V_{IN}	Input voltage relative to GND ^(2,3)		-0.5 to $V_{CC} + 0.5$	V
V_{TS}	Voltage applied to 3-state output ^(2,3)		-0.5 to $V_{CC} + 0.5$	V
T_{STG}	Storage temperature (ambient)		-65 to +150	°C
T_J	Junction temperature	Plastic packages	+125	°C

Notes:

1. Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time may affect device reliability.
2. Maximum DC overshoot (above V_{CC}) or undershoot (below GND) must be limited to either 0.5V or 10 mA, whichever is easier to achieve.
3. Maximum AC (during transitions) conditions are as follows; the device pins may undershoot to -2.0V or overshoot to +7.0V, provided this overshoot or undershoot lasts no more than 11 ns with a forcing current no greater than 100 mA.
4. For soldering guidelines, see the Package Information on the Xilinx website.

Spartan Family Recommended Operating Conditions

Symbol	Description		Min	Max	Units
V_{CC}	Supply voltage relative to GND, $T_J = 0^{\circ}\text{C}$ to $+85^{\circ}\text{C}$	Commercial	4.75	5.25	V
	Supply voltage relative to GND, $T_J = -40^{\circ}\text{C}$ to $+100^{\circ}\text{C}$ ⁽¹⁾	Industrial	4.5	5.5	V
V_{IH}	High-level input voltage ⁽²⁾	TTL inputs	2.0	V_{CC}	V
		CMOS inputs	70%	100%	V_{CC}
V_{IL}	Low-level input voltage ⁽²⁾	TTL inputs	0	0.8	V
		CMOS inputs	0	20%	V_{CC}
T_{IN}	Input signal transition time		-	250	ns

Notes:

1. At junction temperatures above those listed as Recommended Operating Conditions, all delay parameters increase by 0.35% per °C.
2. Input and output measurement thresholds are: 1.5V for TTL and 2.5V for CMOS.

Spartan-XL Family Detailed Specifications

Definition of Terms

In the following tables, some specifications may be designated as Advance or Preliminary. These terms are defined as follows:

Advance: Initial estimates based on simulation and/or extrapolation from other speed grades, devices, or device families. Values are subject to change. Use as estimates, not for production.

Preliminary: Based on preliminary characterization. Further changes are not expected.

Unmarked: Specifications not identified as either Advance or Preliminary are to be considered Final.

Notwithstanding the definition of the above terms, all specifications are subject to change without notice.

Except for pin-to-pin input and output parameters, the AC parameter delay specifications included in this document are derived from measuring internal test patterns. All specifications are representative of worst-case supply voltage and junction temperature conditions. The parameters included are common to popular designs and typical applications.

Spartan-XL Family Absolute Maximum Ratings⁽¹⁾

Symbol	Description		Value	Units
V_{CC}	Supply voltage relative to GND		−0.5 to 4.0	V
V_{IN}	Input voltage relative to GND	5V Tolerant I/O Checked ^(2, 3)	−0.5 to 5.5	V
		Not 5V Tolerant I/Os ^(4, 5)	−0.5 to $V_{CC} + 0.5$	V
V_{TS}	Voltage applied to 3-state output	5V Tolerant I/O Checked ^(2, 3)	−0.5 to 5.5	V
		Not 5V Tolerant I/Os ^(4, 5)	−0.5 to $V_{CC} + 0.5$	V
T_{STG}	Storage temperature (ambient)		−65 to +150	°C
T_J	Junction temperature	Plastic packages	+125	°C

Notes:

- Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time may affect device reliability.
- With 5V Tolerant I/Os selected, the Maximum DC overshoot must be limited to either +5.5V or 10 mA and undershoot (below GND) must be limited to either 0.5V or 10 mA, whichever is easier to achieve.
- With 5V Tolerant I/Os selected, the Maximum AC (during transitions) conditions are as follows; the device pins may undershoot to −2.0V or overshoot to +7.0V, provided this overshoot or undershoot lasts no more than 11 ns with a forcing current no greater than 100 mA.
- Without 5V Tolerant I/Os selected, the Maximum DC overshoot or undershoot must be limited to either 0.5V or 10 mA, whichever is easier to achieve.
- Without 5V Tolerant I/Os selected, the Maximum AC conditions are as follows; the device pins may undershoot to −2.0V or overshoot to $V_{CC} + 2.0V$, provided this overshoot or undershoot lasts no more than 11 ns with a forcing current no greater than 100 mA.
- For soldering guidelines, see the Package Information on the Xilinx website.

Spartan-XL Family Recommended Operating Conditions

Symbol	Description		Min	Max	Units
V_{CC}	Supply voltage relative to GND, $T_J = 0^{\circ}\text{C}$ to $+85^{\circ}\text{C}$	Commercial	3.0	3.6	V
	Supply voltage relative to GND, $T_J = -40^{\circ}\text{C}$ to $+100^{\circ}\text{C}$ ⁽¹⁾	Industrial	3.0	3.6	V
V_{IH}	High-level input voltage ⁽²⁾		50% of V_{CC}	5.5	V
V_{IL}	Low-level input voltage ⁽²⁾		0	30% of V_{CC}	V
T_{IN}	Input signal transition time		-	250	ns

Notes:

- At junction temperatures above those listed as Operating Conditions, all delay parameters increase by 0.35% per °C.
- Input and output measurement threshold is ~50% of V_{CC} .

Spartan-XL Family CLB RAM Synchronous (Edge-Triggered) Write Operation Guidelines (cont.)

All devices are 100% functionally tested. Internal timing parameters are derived from measuring internal test patterns. Listed below are representative values. For more specific, more precise, and worst-case guaranteed data, use the values reported by the static timing analyzer (TRCE

in the Xilinx Development System) and back-annotated to the simulation netlist. All timing parameters assume worst-case operating conditions (supply voltage and junction temperature). Values apply to all Spartan-XL devices and are expressed in nanoseconds unless otherwise noted.

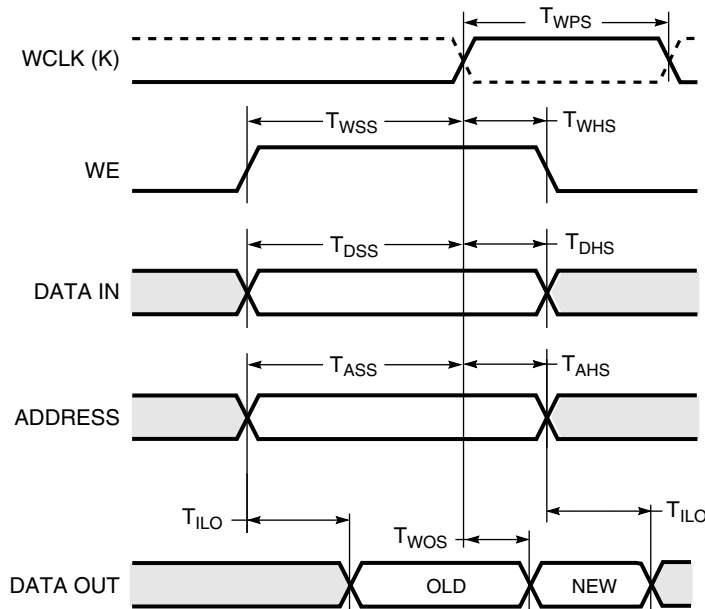
Symbol	Dual Port RAM	Size	-5		-4		Units
			Min	Max	Min	Max	
Write Operation ⁽¹⁾							
T _{WCDS}	Address write cycle time (clock K period)	16x1	7.7	-	8.4	-	ns
T _{WPDS}	Clock K pulse width (active edge)	16x1	3.1	-	3.6	-	ns
T _{ASDS}	Address setup time before clock K	16x1	1.3	-	1.5	-	ns
T _{DSDS}	DIN setup time before clock K	16x1	1.7	-	2.0	-	ns
T _{WSDS}	WE setup time before clock K	16x1	1.4	-	1.6	-	ns
	All hold times after clock K	16x1	0	-	0	-	ns
T _{WODS}	Data valid after clock K	16x1	-	5.2	-	6.1	ns

Notes:

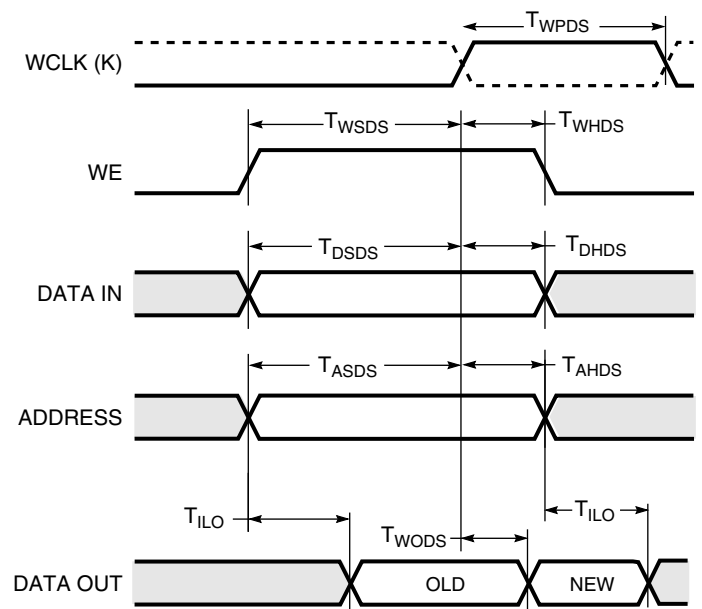
1. Read Operation timing for 16 x 1 dual-port RAM option is identical to 16 x 2 single-port RAM timing

Spartan-XL Family CLB RAM Synchronous (Edge-Triggered) Write Timing

Single Port



Dual Port



DS060_34_011300

Spartan-XL Family Pin-to-Pin Input Parameter Guidelines

All devices are 100% functionally tested. Pin-to-pin timing parameters are derived from measuring external and internal test patterns and are guaranteed over worst-case operating conditions (supply voltage and junction temperature). Listed below are representative values for typical pin locations and normal clock loading.

ating conditions (supply voltage and junction temperature). Listed below are representative values for typical pin locations and normal clock loading.

Spartan-XL Family Setup and Hold

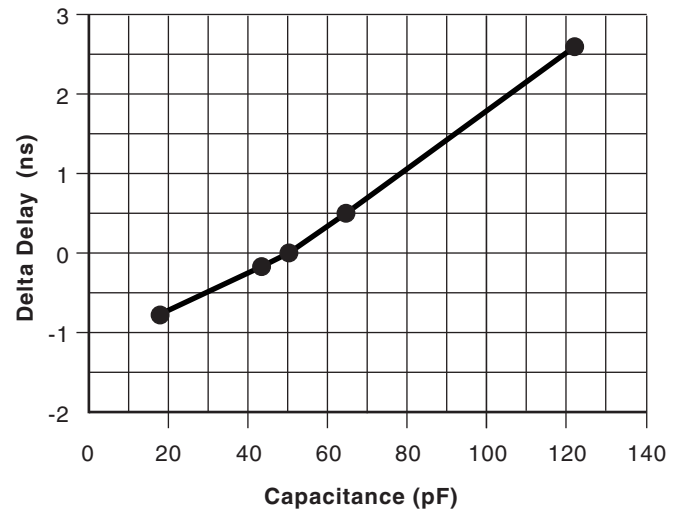
Symbol	Description	Device	Speed Grade		Units
			-5	-4	
			Max	Max	
Input Setup/Hold Times Using Global Clock and IFF					
T_{SUF}/T_{HF}	No Delay	XCS05XL	1.1/2.0	1.6/2.6	ns
		XCS10XL	1.0/2.2	1.5/2.8	ns
		XCS20XL	0.9/2.4	1.4/3.0	ns
		XCS30XL	0.8/2.6	1.3/3.2	ns
		XCS40XL	0.7/2.8	1.2/3.4	ns
T_{SU}/T_H	Full Delay	XCS05XL	3.9/0.0	5.1/0.0	ns
		XCS10XL	4.1/0.0	5.3/0.0	ns
		XCS20XL	4.3/0.0	5.5/0.0	ns
		XCS30XL	4.5/0.0	5.7/0.0	ns
		XCS40XL	4.7/0.0	5.9/0.0	ns

Notes:

1. IFF = Input Flip-Flop or Latch
2. Setup time is measured with the fastest route and the lightest load. Hold time is measured using the furthest distance and a reference load of one clock pin per IOB/CLB.

Capacitive Load Factor

Figure 35 shows the relationship between I/O output delay and load capacitance. It allows a user to adjust the specified output delay if the load capacitance is different than 50 pF. For example, if the actual load capacitance is 120 pF, add 2.5 ns to the specified delay. If the load capacitance is 20 pF, subtract 0.8 ns from the specified output delay. Figure 35 is usable over the specified operating conditions of voltage and temperature and is independent of the output slew rate control.



DS060_35_080400

Figure 35: Delay Factor at Various Capacitive Loads

Table 18: Pin Descriptions (Continued)

Pin Name	I/O During Config.	I/O After Config.	Pin Description
$\overline{\text{PWRDWN}}$	I	I	$\overline{\text{PWRDWN}}$ is an active Low input that forces the FPGA into the Power Down state and reduces power consumption. When $\overline{\text{PWRDWN}}$ is Low, the FPGA disables all I/O and initializes all flip-flops. All inputs are interpreted as Low independent of their actual level. VCC must be maintained, and the configuration data is maintained. $\overline{\text{PWRDWN}}$ halts configuration if asserted before or during configuration, and re-starts configuration when removed. When $\overline{\text{PWRDWN}}$ returns High, the FPGA becomes operational by first enabling the inputs and flip-flops and then enabling the outputs. $\overline{\text{PWRDWN}}$ has a default internal pull-up resistor.
User I/O Pins That Can Have Special Functions			
TDO	O	O	If boundary scan is used, this pin is the Test Data Output. If boundary scan is not used, this pin is a 3-state output without a register, after configuration is completed. To use this pin, place the library component TDO instead of the usual pad symbol. An output buffer must still be used.
TDI, TCK, TMS	I	I/O or I (JTAG)	If boundary scan is used, these pins are Test Data In, Test Clock, and Test Mode Select inputs respectively. They come directly from the pads, bypassing the IOBs. These pins can also be used as inputs to the CLB logic after configuration is completed. If the BSCAN symbol is not placed in the design, all boundary scan functions are inhibited once configuration is completed, and these pins become user-programmable I/O. In this case, they must be called out by special library elements. To use these pins, place the library components TDI, TCK, and TMS instead of the usual pad symbols. Input or output buffers must still be used.
HDC	O	I/O	High During Configuration (HDC) is driven High until the I/O go active. It is available as a control output indicating that configuration is not yet completed. After configuration, HDC is a user-programmable I/O pin.
$\overline{\text{LDC}}$	O	I/O	Low During Configuration ($\overline{\text{LDC}}$) is driven Low until the I/O go active. It is available as a control output indicating that configuration is not yet completed. After configuration, $\overline{\text{LDC}}$ is a user-programmable I/O pin.
$\overline{\text{INIT}}$	I/O	I/O	Before and during configuration, $\overline{\text{INIT}}$ is a bidirectional signal. A 1 k Ω to 10 k Ω external pull-up resistor is recommended. As an active Low open-drain output, $\overline{\text{INIT}}$ is held Low during the power stabilization and internal clearing of the configuration memory. As an active Low input, it can be used to hold the FPGA in the internal WAIT state before the start of configuration. Master mode devices stay in a WAIT state an additional 30 to 300 μs after INIT has gone High. During configuration, a Low on this output indicates that a configuration data error has occurred. After the I/O go active, $\overline{\text{INIT}}$ is a user-programmable I/O pin.
PGCK1 - PGCK4 (Spartan)	Weak Pull-up	I or I/O	Four Primary Global inputs each drive a dedicated internal global net with short delay and minimal skew. If not used to drive a global buffer, any of these pins is a user-programmable I/O. The PGCK1-PGCK4 pins drive the four Primary Global Buffers. Any input pad symbol connected directly to the input of a BUFPGP symbol is automatically placed on one of these pins.

XCS05 and XCS05XL Device Pinouts

XCS05/XL Pad Name	PC84 ⁽⁴⁾	VQ100	Bndry Scan
I/O	P70	P71	238 ⁽³⁾
I/O (D0 ⁽²⁾ , DIN)	P71	P72	241 ⁽³⁾
I/O, SGCK4 ⁽¹⁾ , GCK6 ⁽²⁾ (DOUT)	P72	P73	244 ⁽³⁾
CCLK	P73	P74	-
VCC	P74	P75	-
O, TDO	P75	P76	0
GND	P76	P77	-
I/O	P77	P78	2
I/O, PGCK4 ⁽¹⁾ , GCK7 ⁽²⁾	P78	P79	5
I/O (CS1 ⁽²⁾)	P79	P80	8
I/O	P80	P81	11
I/O	P81	P82	14
I/O	P82	P83	17
I/O	-	P84	20
I/O	-	P85	23
I/O	P83	P86	26
I/O	P84	P87	29
GND	P1	P88	-

Notes:

1. 5V Spartan family only
2. 3V Spartan-XL family only
3. The "PWRDWN" on the XCS05XL is not part of the Boundary Scan chain. For the XCS05XL, subtract 1 from all Boundary Scan numbers from GCK3 on (127 and higher).
4. PC84 package discontinued by [PDN2004-01](#)

XCS10 and XCS10XL Device Pinouts

XCS10/XL Pad Name	PC84 ⁽⁴⁾	VQ100	CS144 ^(2,4)	TQ144	Bndry Scan
VCC	P2	P89	D7	P128	-
I/O	P3	P90	A6	P129	44
I/O	P4	P91	B6	P130	47
I/O	-	P92	C6	P131	50
I/O	-	P93	D6	P132	53
I/O	P5	P94	A5	P133	56
I/O	P6	P95	B5	P134	59
I/O	-	-	C5	P135	62
I/O	-	-	D5	P136	65
GND	-	-	A4	P137	-
I/O	P7	P96	B4	P138	68
I/O	P8	P97	C4	P139	71
I/O	-	-	A3	P140	74
I/O	-	-	B3	P141	77
I/O	P9	P98	C3	P142	80

XCS10 and XCS10XL Device Pinouts

XCS10/XL Pad Name	PC84 ⁽⁴⁾	VQ100	CS144 ^(2,4)	TQ144	Bndry Scan
I/O, SGCK1 ⁽¹⁾ GCK8 ⁽²⁾	P10	P99	A2	P143	83
VCC	P11	P100	B2	P144	-
GND	P12	P1	A1	P1	-
I/O, PGCK1 ⁽¹⁾ GCK1 ⁽²⁾	P13	P2	B1	P2	86
I/O	P14	P3	C2	P3	89
I/O	-	-	C1	P4	92
I/O	-	-	D4	P5	95
I/O, TDI	P15	P4	D3	P6	98
I/O, TCK	P16	P5	D2	P7	101
GND	-	-	D1	P8	-
I/O	-	-	E4	P9	104
I/O	-	-	E3	P10	107
I/O, TMS	P17	P6	E2	P11	110
I/O	P18	P7	E1	P12	113
I/O	-	-	F4	P13	116
I/O	-	P8	F3	P14	119
I/O	P19	P9	F2	P15	122
I/O	P20	P10	F1	P16	125
GND	P21	P11	G2	P17	-
VCC	P22	P12	G1	P18	-
I/O	P23	P13	G3	P19	128
I/O	P24	P14	G4	P20	131
I/O	-	P15	H1	P21	134
I/O	-	-	H2	P22	137
I/O	P25	P16	H3	P23	140
I/O	P26	P17	H4	P24	143
I/O	-	-	J1	P25	146
I/O	-	-	J2	P26	149
GND	-	-	J3	P27	-
I/O	P27	P18	J4	P28	152
I/O	-	P19	K1	P29	155
I/O	-	-	K2	P30	158
I/O	-	-	K3	P31	161
I/O	P28	P20	L1	P32	164
I/O, SGCK2 ⁽¹⁾ GCK2 ⁽²⁾	P29	P21	L2	P33	167
Not Connected ⁽¹⁾ M1 ⁽²⁾	P30	P22	L3	P34	170
GND	P31	P23	M1	P35	-
MODE ⁽¹⁾ , M0 ⁽²⁾	P32	P24	M2	P36	173

XCS10 and XCS10XL Device Pinouts

XCS10/XL Pad Name	PC84(4)	VQ100	CS144(2,4)	TQ144	Bndry Scan
VCC	P33	P25	N1	P37	-
Not Connect-ed ⁽¹⁾	P34	P26	N2	P38	174 ⁽¹⁾
PWRDWN ⁽²⁾					
I/O, PGCK2 ⁽¹⁾ GCK3 ⁽²⁾	P35	P27	M3	P39	175 ⁽³⁾
I/O (HDC)	P36	P28	N3	P40	178 ⁽³⁾
I/O	-	-	K4	P41	181 ⁽³⁾
I/O	-	-	L4	P42	184 ⁽³⁾
I/O	-	P29	M4	P43	187 ⁽³⁾
I/O (LDC)	P37	P30	N4	P44	190 ⁽³⁾
GND	-	-	K5	P45	-
I/O	-	-	L5	P46	193 ⁽³⁾
I/O	-	-	M5	P47	196 ⁽³⁾
I/O	P38	P31	N5	P48	199 ⁽³⁾
I/O	P39	P32	K6	P49	202 ⁽³⁾
I/O	-	P33	L6	P50	205 ⁽³⁾
I/O	-	P34	M6	P51	208 ⁽³⁾
I/O	P40	P35	N6	P52	211 ⁽³⁾
I/O (INIT)	P41	P36	M7	P53	214 ⁽³⁾
VCC	P42	P37	N7	P54	-
GND	P43	P38	L7	P55	-
I/O	P44	P39	K7	P56	217 ⁽³⁾
I/O	P45	P40	N8	P57	220 ⁽³⁾
I/O	-	P41	M8	P58	223 ⁽³⁾
I/O	-	P42	L8	P59	226 ⁽³⁾
I/O	P46	P43	K8	P60	229 ⁽³⁾
I/O	P47	P44	N9	P61	232 ⁽³⁾
I/O	-	-	M9	P62	235 ⁽³⁾
I/O	-	-	L9	P63	238 ⁽³⁾
GND	-	-	K9	P64	-
I/O	P48	P45	N10	P65	241 ⁽³⁾
I/O	P49	P46	M10	P66	244 ⁽³⁾
I/O	-	-	L10	P67	247 ⁽³⁾
I/O	-	-	N11	P68	250 ⁽³⁾
I/O	P50	P47	M11	P69	253 ⁽³⁾
I/O, SGCK3 ⁽¹⁾ GCK4 ⁽²⁾	P51	P48	L11	P70	256 ⁽³⁾
GND	P52	P49	N12	P71	-
DONE	P53	P50	M12	P72	-
VCC	P54	P51	N13	P73	-
PROGRAM	P55	P52	M13	P74	-
I/O (D7 ⁽²⁾)	P56	P53	L12	P75	259 ⁽³⁾

XCS10 and XCS10XL Device Pinouts

XCS10/XL Pad Name	PC84(4)	VQ100	CS144(2,4)	TQ144	Bndry Scan
I/O, PGCK3 ⁽¹⁾ GCK5 ⁽²⁾	P57	P54	L13	P76	262 ⁽³⁾
I/O	-	-	K10	P77	265 ⁽³⁾
I/O	-	-	K11	P78	268 ⁽³⁾
I/O (D6 ⁽²⁾)	P58	P55	K12	P79	271 ⁽³⁾
I/O	-	P56	K13	P80	274 ⁽³⁾
GND	-	-	J10	P81	-
I/O	-	-	J11	P82	277 ⁽³⁾
I/O	-	-	J12	P83	280 ⁽³⁾
I/O (D5 ⁽²⁾)	P59	P57	J13	P84	283 ⁽³⁾
I/O	P60	P58	H10	P85	286 ⁽³⁾
I/O	-	P59	H11	P86	289 ⁽³⁾
I/O	-	P60	H12	P87	292 ⁽³⁾
I/O (D4 ⁽²⁾)	P61	P61	H13	P88	295 ⁽³⁾
I/O	P62	P62	G12	P89	298 ⁽³⁾
VCC	P63	P63	G13	P90	-
GND	P64	P64	G11	P91	-
I/O (D3 ⁽²⁾)	P65	P65	G10	P92	301 ⁽³⁾
I/O	P66	P66	F13	P93	304 ⁽³⁾
I/O	-	P67	F12	P94	307 ⁽³⁾
I/O	-	-	F11	P95	310 ⁽³⁾
I/O (D2 ⁽²⁾)	P67	P68	F10	P96	313 ⁽³⁾
I/O	P68	P69	E13	P97	316 ⁽³⁾
I/O	-	-	E12	P98	319 ⁽³⁾
I/O	-	-	E11	P99	322 ⁽³⁾
GND	-	-	E10	P100	-
I/O (D1 ⁽²⁾)	P69	P70	D13	P101	325 ⁽³⁾
I/O	P70	P71	D12	P102	328 ⁽³⁾
I/O	-	-	D11	P103	331 ⁽³⁾
I/O	-	-	C13	P104	334 ⁽³⁾
I/O (D0 ⁽²⁾ , DIN)	P71	P72	C12	P105	337 ⁽³⁾
I/O, SGCK4 ⁽¹⁾ GCK6 ⁽²⁾ (DOUT)	P72	P73	C11	P106	340 ⁽³⁾
CCLK	P73	P74	B13	P107	-
VCC	P74	P75	B12	P108	-
O, TDO	P75	P76	A13	P109	0
GND	P76	P77	A12	P110	-
I/O	P77	P78	B11	P111	2
I/O, PGCK4 ⁽¹⁾ GCK7 ⁽²⁾	P78	P79	A11	P112	5
I/O	-	-	D10	P113	8
I/O	-	-	C10	P114	11
I/O (CS1 ⁽²⁾)	P79	P80	B10	P115	14

XCS20 and XCS20XL Device Pinouts

XCS20/XL Pad Name	VQ100	CS144 ^(2,4)	TQ144	PQ208	Bndry Scan
I/O	-	F4	P13	P21	170
I/O	P8	F3	P14	P22	173
I/O	P9	F2	P15	P23	176
I/O	P10	F1	P16	P24	179
GND	P11	G2	P17	P25	-
VCC	P12	G1	P18	P26	-
I/O	P13	G3	P19	P27	182
I/O	P14	G4	P20	P28	185
I/O	P15	H1	P21	P29	188
I/O	-	H2	P22	P30	191
I/O	-	-	-	P31	194
I/O	-	-	-	P32	197
VCC ⁽²⁾	-	-	-	P33	-
I/O	P16	H3	P23	P34	200
I/O	P17	H4	P24	P35	203
I/O	-	J1	P25	P36	206
I/O	-	J2	P26	P37	209
GND	-	J3	P27	P38	-
I/O	-	-	-	P40	212
I/O	-	-	-	P41	215
I/O	-	-	-	P42	218
I/O	-	-	-	P43	221
I/O	P18	J4	P28	P44	224
I/O	P19	K1	P29	P45	227
I/O	-	K2	P30	P46	230
I/O	-	K3	P31	P47	233
I/O	P20	L1	P32	P48	236
I/O, SGCK2 ⁽¹⁾ , GCK2 ⁽²⁾	P21	L2	P33	P49	239
Not Connected ⁽¹⁾ M1 ⁽²⁾	P22	L3	P34	P50	242
GND	P23	M1	P35	P51	-
MODE ⁽¹⁾ , M0 ⁽²⁾	P24	M2	P36	P52	245
VCC	P25	N1	P37	P53	-
Not Connected ⁽¹⁾ PWRDWN ⁽²⁾	P26	N2	P38	P54	246 ⁽¹⁾
I/O, PGCK2 ⁽¹⁾ , GCK3 ⁽²⁾	P27	M3	P39	P55	247 ⁽³⁾
I/O (HDC)	P28	N3	P40	P56	250 ⁽³⁾
I/O	-	K4	P41	P57	253 ⁽³⁾
I/O	-	L4	P42	P58	256 ⁽³⁾
I/O	P29	M4	P43	P59	259 ⁽³⁾

XCS20 and XCS20XL Device Pinouts

XCS20/XL Pad Name	VQ100	CS144 ^(2,4)	TQ144	PQ208	Bndry Scan
I/O (LDC)	P30	N4	P44	P60	262 ⁽³⁾
I/O	-	-	-	P61	265 ⁽³⁾
I/O	-	-	-	P62	268 ⁽³⁾
I/O	-	-	-	P63	271 ⁽³⁾
I/O	-	-	-	P64	274 ⁽³⁾
GND	-	K5	P45	P66	-
I/O	-	L5	P46	P67	277 ⁽³⁾
I/O	-	M5	P47	P68	280 ⁽³⁾
I/O	P31	N5	P48	P69	283 ⁽³⁾
I/O	P32	K6	P49	P70	286 ⁽³⁾
VCC ⁽²⁾	-	-	-	P71	-
I/O	-	-	-	P72	289 ⁽³⁾
I/O	-	-	-	P73	292 ⁽³⁾
I/O	P33	L6	P50	P74	295 ⁽³⁾
I/O	P34	M6	P51	P75	298 ⁽³⁾
I/O	P35	N6	P52	P76	301 ⁽³⁾
I/O (INIT)	P36	M7	P53	P77	304 ⁽³⁾
VCC	P37	N7	P54	P78	-
GND	P38	L7	P55	P79	-
I/O	P39	K7	P56	P80	307 ⁽³⁾
I/O	P40	N8	P57	P81	310 ⁽³⁾
I/O	P41	M8	P58	P82	313 ⁽³⁾
I/O	P42	L8	P59	P83	316 ⁽³⁾
I/O	-	-	-	P84	319 ⁽³⁾
I/O	-	-	-	P85	322 ⁽³⁾
VCC ⁽²⁾	-	-	-	P86	-
I/O	P43	K8	P60	P87	325 ⁽³⁾
I/O	P44	N9	P61	P88	328 ⁽³⁾
I/O	-	M9	P62	P89	331 ⁽³⁾
I/O	-	L9	P63	P90	334 ⁽³⁾
GND	-	K9	P64	P91	-
I/O	-	-	-	P93	337 ⁽³⁾
I/O	-	-	-	P94	340 ⁽³⁾
I/O	-	-	-	P95	343 ⁽³⁾
I/O	-	-	-	P96	346 ⁽³⁾
I/O	P45	N10	P65	P97	349 ⁽³⁾
I/O	P46	M10	P66	P98	352 ⁽³⁾
I/O	-	L10	P67	P99	355 ⁽³⁾
I/O	-	N11	P68	P100	358 ⁽³⁾
I/O	P47	M11	P69	P101	361 ⁽³⁾
I/O, SGCK3 ⁽¹⁾ , GCK4 ⁽²⁾	P48	L11	P70	P102	364 ⁽³⁾
GND	P49	N12	P71	P103	-
DONE	P50	M12	P72	P104	-
VCC	P51	N13	P73	P105	-

XCS20 and XCS20XL Device Pinouts

XCS20/XL Pad Name	VQ100	CS144 ^(2,4)	TQ144	PQ208	Bndry Scan
PROGRAM	P52	M13	P74	P106	-
I/O (D7 ⁽²⁾)	P53	L12	P75	P107	367 ⁽³⁾
I/O, PGCK3 ⁽¹⁾ , GCK5 ⁽²⁾	P54	L13	P76	P108	370 ⁽³⁾
I/O	-	K10	P77	P109	373 ⁽³⁾
I/O	-	K11	P78	P110	376 ⁽³⁾
I/O (D6 ⁽²⁾)	P55	K12	P79	P112	379 ⁽³⁾
I/O	P56	K13	P80	P113	382 ⁽³⁾
I/O	-	-	-	P114	385 ⁽³⁾
I/O	-	-	-	P115	388 ⁽³⁾
I/O	-	-	-	P116	391 ⁽³⁾
I/O	-	-	-	P117	394 ⁽³⁾
GND	-	J10	P81	P118	-
I/O	-	J11	P82	P119	397 ⁽³⁾
I/O	-	J12	P83	P120	400 ⁽³⁾
VCC ⁽²⁾	-	-	-	P121	-
I/O (D5 ⁽²⁾)	P57	J13	P84	P122	403 ⁽³⁾
I/O	P58	H10	P85	P123	406 ⁽³⁾
I/O	-	-	-	P124	409 ⁽³⁾
I/O	-	-	-	P125	412 ⁽³⁾
I/O	P59	H11	P86	P126	415 ⁽³⁾
I/O	P60	H12	P87	P127	418 ⁽³⁾
I/O (D4 ⁽²⁾)	P61	H13	P88	P128	421 ⁽³⁾
I/O	P62	G12	P89	P129	424 ⁽³⁾
VCC	P63	G13	P90	P130	-
GND	P64	G11	P91	P131	-
I/O (D3 ⁽²⁾)	P65	G10	P92	P132	427 ⁽³⁾
I/O	P66	F13	P93	P133	430 ⁽³⁾
I/O	P67	F12	P94	P134	433 ⁽³⁾
I/O	-	F11	P95	P135	436 ⁽³⁾
I/O	-	-	-	P136	439 ⁽³⁾
I/O	-	-	-	P137	442 ⁽³⁾
I/O (D2 ⁽²⁾)	P68	F10	P96	P138	445 ⁽³⁾
I/O	P69	E13	P97	P139	448 ⁽³⁾
VCC ⁽²⁾	-	-	-	P140	-
I/O	-	E12	P98	P141	451 ⁽³⁾
I/O	-	E11	P99	P142	454 ⁽³⁾
GND	-	E10	P100	P143	-
I/O	-	-	-	P145	457 ⁽³⁾
I/O	-	-	-	P146	460 ⁽³⁾
I/O	-	-	-	P147	463 ⁽³⁾
I/O	-	-	-	P148	466 ⁽³⁾
I/O (D1 ⁽²⁾)	P70	D13	P101	P149	469 ⁽³⁾
I/O	P71	D12	P102	P150	472 ⁽³⁾
I/O	-	D11	P103	P151	475 ⁽³⁾

XCS20 and XCS20XL Device Pinouts

XCS20/XL Pad Name	VQ100	CS144 ^(2,4)	TQ144	PQ208	Bndry Scan
I/O	-	C13	P104	P152	478 ⁽³⁾
I/O (D0 ⁽²⁾ , DIN)	P72	C12	P105	P153	481 ⁽³⁾
I/O, SGCK4 ⁽¹⁾ , GCK6 ⁽²⁾ (DOUT)	P73	C11	P106	P154	484 ⁽³⁾
CCLK	P74	B13	P107	P155	-
VCC	P75	B12	P108	P156	-
O, TDO	P76	A13	P109	P157	0
GND	P77	A12	P110	P158	-
I/O	P78	B11	P111	P159	2
I/O, PGCK4 ⁽¹⁾ , GCK7 ⁽²⁾	P79	A11	P112	P160	5
I/O	-	D10	P113	P161	8
I/O	-	C10	P114	P162	11
I/O (CS1 ⁽²⁾)	P80	B10	P115	P163	14
I/O	P81	A10	P116	P164	17
I/O	-	D9	P117	P166	20
I/O	-	-	-	P167	23
I/O	-	-	-	P168	26
I/O	-	-	-	P169	29
GND	-	C9	P118	P170	-
I/O	-	B9	P119	P171	32
I/O	-	A9	P120	P172	35
VCC ⁽²⁾	-	-	-	P173	-
I/O	P82	D8	P121	P174	38
I/O	P83	C8	P122	P175	41
I/O	-	-	-	P176	44
I/O	-	-	-	P177	47
I/O	P84	B8	P123	P178	50
I/O	P85	A8	P124	P179	53
I/O	P86	B7	P125	P180	56
I/O	P87	A7	P126	P181	59
GND	P88	C7	P127	P182	-

2/8/00

XCS30 and XCS30XL Device Pinouts (Continued)

XCS30/XL Pad Name	VQ100 ⁽⁵⁾	TQ144	PQ208	PQ240	BG256 ⁽⁵⁾	CS280 ^(2,5)	Bndry Scan
I/O	-	-	P124	P144	M20	L19	493 ⁽³⁾
I/O	-	-	P125	P145	L19	L18	496 ⁽³⁾
I/O	P59	P86	P126	P146	L18	L17	499 ⁽³⁾
I/O	P60	P87	P127	P147	L20	L16	502 ⁽³⁾
I/O (D4 ⁽²⁾)	P61	P88	P128	P148	K20	K19	505 ⁽³⁾
I/O	P62	P89	P129	P149	K19	K18	508 ⁽³⁾
VCC	P63	P90	P130	P150	VCC ⁽⁴⁾	K17	-
GND	P64	P91	P131	P151	GND ⁽⁴⁾	GND ⁽⁴⁾	-
I/O (D3 ⁽²⁾)	P65	P92	P132	P152	K18	K16	511 ⁽³⁾
I/O	P66	P93	P133	P153	K17	K15	514 ⁽³⁾
I/O	P67	P94	P134	P154	J20	J19	517 ⁽³⁾
I/O	-	P95	P135	P155	J19	J18	520 ⁽³⁾
I/O	-	-	P136	P156	J18	J17	523 ⁽³⁾
I/O	-	-	P137	P157	J17	J16	526 ⁽³⁾
I/O (D2 ⁽²⁾)	P68	P96	P138	P159	H19	H17	529 ⁽³⁾
I/O	P69	P97	P139	P160	H18	H16	532 ⁽³⁾
VCC	-	-	P140	P161	VCC ⁽⁴⁾	G19	-
I/O	-	P98	P141	P162	G19	G18	535 ⁽³⁾
I/O	-	P99	P142	P163	F20	G17	538 ⁽³⁾
I/O	-	-	-	P164	G18	G16	541 ⁽³⁾
I/O	-	-	-	P165	F19	F19	544 ⁽³⁾
GND	-	P100	P143	P166	GND ⁽⁴⁾	GND ⁽⁴⁾	-
I/O	-	-	-	P167	F18	F18	547 ⁽³⁾
I/O	-	-	P144	P168	E19	F17	550 ⁽³⁾
I/O	-	-	P145	P169	D20	F16	553 ⁽³⁾
I/O	-	-	P146	P170	E18	F15	556 ⁽³⁾
I/O	-	-	P147	P171	D19	E19	559 ⁽³⁾
I/O	-	-	P148	P172	C20	E17	562 ⁽³⁾
I/O (D1 ⁽²⁾)	P70	P101	P149	P173	E17	E16	565 ⁽³⁾
I/O	P71	P102	P150	P174	D18	D19	568 ⁽³⁾
I/O	-	P103	P151	P175	C19	C19	571 ⁽³⁾
I/O	-	P104	P152	P176	B20	B19	574 ⁽³⁾
I/O (D0 ⁽²⁾ , DIN)	P72	P105	P153	P177	C18	C18	577 ⁽³⁾
I/O, SGCK4 ⁽¹⁾ , GCK6 ⁽²⁾ (DOUT)	P73	P106	P154	P178	B19	B18	580 ⁽³⁾
CCLK	P74	P107	P155	P179	A20	A19	-
VCC	P75	P108	P156	P180	VCC ⁽⁴⁾	C17	-
O, TDO	P76	P109	P157	P181	A19	B17	0
GND	P77	P110	P158	P182	GND ⁽⁴⁾	GND ⁽⁴⁾	-
I/O	P78	P111	P159	P183	B18	A18	2
I/O, PGCK4 ⁽¹⁾ , GCK7 ⁽²⁾	P79	P112	P160	P184	B17	A17	5
I/O	-	P113	P161	P185	C17	D16	8
I/O	-	P114	P162	P186	D16	C16	11
I/O (CS1 ⁽²⁾)	P80	P115	P163	P187	A18	B16	14
I/O	P81	P116	P164	P188	A17	A16	17
I/O	-	-	P165	P189	C16	D15	20

XCS30 and XCS30XL Device Pinouts (Continued)

XCS30/XL Pad Name	VQ100 ⁽⁵⁾	TQ144	PQ208	PQ240	BG256 ⁽⁵⁾	CS280 ^(2,5)	Bndry Scan
I/O	-	-	-	P190	B16	A15	23
I/O	-	P117	P166	P191	A16	E14	26
I/O	-	-	P167	P192	C15	C14	29
I/O	-	-	P168	P193	B15	B14	32
I/O	-	-	P169	P194	A15	D14	35
GND	-	P118	P170	P196	GND ⁽⁴⁾	GND ⁽⁴⁾	-
I/O	-	P119	P171	P197	B14	A14	38
I/O	-	P120	P172	P198	A14	C13	41
I/O	-	-	-	P199	C13	B13	44
I/O	-	-	-	P200	B13	A13	47
VCC	-	-	P173	P201	VCC ⁽⁴⁾	D13	-
I/O	P82	P121	P174	P202	C12	B12	50
I/O	P83	P122	P175	P203	B12	D12	53
I/O	-	-	P176	P205	A12	A11	56
I/O	-	-	P177	P206	B11	B11	59
I/O	P84	P123	P178	P207	C11	C11	62
I/O	P85	P124	P179	P208	A11	D11	65
I/O	P86	P125	P180	P209	A10	A10	68
I/O	P87	P126	P181	P210	B10	B10	71
GND	P88	P127	P182	P211	GND ⁽⁴⁾	GND ⁽⁴⁾	-

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Notes:

1. 5V Spartan family only
2. 3V Spartan-XL family only
3. The "PWRDWN" on the XCS30XL is not part of the Boundary Scan chain. For the XCS30XL, subtract 1 from all Boundary Scan numbers from GCK3 on (295 and higher).
4. Pads labeled GND⁽⁴⁾ or VCC⁽⁴⁾ are internally bonded to Ground or VCC planes within the package.
5. CS280 package, and VQ100 and BG256 packages for XCS30 only, discontinued by [PDN2004-01](#)

Additional XCS30/XL Package Pins

PQ240

GND Pins					
P22	P37	P83	P98	P143	P158
P204	P219	-	-	-	-
Not Connected Pins					
P195	-	-	-	-	-

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BG256

VCC Pins					
C14	D6	D7	D11	D14	D15
E20	F1	F4	F17	G4	G17
K4	L17	P4	P17	P19	R2
R4	R17	U6	U7	U10	U14
U15	V7	W20	-	-	-

GND Pins

A1	B7	D4	D8	D13	D17
G20	H4	H17	N3	N4	N17
U4	U8	U13	U17	W14	-
Not Connected Pins					
A7	A13	C8	D12	H20	J3
J4	M4	M19	V9	W9	W13
Y13	-	-	-	-	-

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CS280

VCC Pins					
A1	A7	C10	C17	D13	G1
G1	G19	K2	K17	M4	N16
T7	U3	U10	U17	W13	-
GND Pins					

CS280

VCC Pins					
E5	E7	E8	E9	E11	E12
E13	G5	G15	H5	H15	J5
J15	L5	L15	M5	M15	N5
N15	R7	R8	R9	R11	R12
R13	-	-	-	-	-
Not Connected Pins					
A4	A12	C8	C12	C15	D1
D2	D5	D8	D17	D18	E15
H2	H3	H18	H19	L4	M1
M16	M18	R2	R4	R5	R15
R17	T8	T15	U5	V8	V12
W12	W16	-	-	-	-
Not Connected Pins (VCC in XCS40XL)					
B5	B15	E3	E18	R3	R18
V5	V15	-	-	-	-

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XCS40 and XCS40XL Device Pinouts

XCS40/XL Pad Name	PQ208	PQ240	BG256	CS280 ^(2,5)	Bndry Scan
VCC	P183	P212	VCC ⁽⁴⁾	VCC ⁽⁴⁾	-
I/O	P184	P213	C10	D10	86
I/O	P185	P214	D10	E10	89
I/O	P186	P215	A9	A9	92
I/O	P187	P216	B9	B9	95
I/O	P188	P217	C9	C9	98
I/O	P189	P218	D9	D9	101
I/O	P190	P220	A8	A8	104
I/O	P191	P221	B8	B8	107
I/O	-	-	C8	C8	110
I/O	-	-	A7	D8	113
VCC	P192	P222	VCC ⁽⁴⁾	VCC ⁽⁴⁾	-
I/O	-	P223	A6	B7	116
I/O	-	P224	C7	C7	119
I/O	P193	P225	B6	D7	122
I/O	P194	P226	A5	A6	125
GND	P195	P227	GND ⁽⁴⁾	GND ⁽⁴⁾	-
I/O	P196	P228	C6	B6	128
I/O	P197	P229	B5	C6	131
I/O	P198	P230	A4	D6	134
I/O	P199	P231	C5	E6	137

XCS40 and XCS40XL Device Pinouts

XCS40/XL Pad Name	PQ208	PQ240	BG256	CS280 ^(2,5)	Bndry Scan
I/O	P200	P232	B4	A5	140
I/O	P201	P233	A3	C5	143
I/O	-	-	-	D5	146
I/O	-	-	-	A4	149
I/O	P202	P234	D5	B4	152
I/O	P203	P235	C4	C4	155
I/O	P204	P236	B3	A3	158
I/O	P205	P237	B2	A2	161
I/O	P206	P238	A2	B3	164
I/O, SGCK1 ⁽¹⁾ , GCK8 ⁽²⁾	P207	P239	C3	B2	167
VCC	P208	P240	VCC ⁽⁴⁾	VCC ⁽⁴⁾	-
GND	P1	P1	GND ⁽⁴⁾	GND ⁽⁴⁾	-
I/O, PGCK1 ⁽¹⁾ , GCK1 ⁽²⁾	P2	P2	B1	C3	170
I/O	P3	P3	C2	C2	173
I/O	P4	P4	D2	B1	176
I/O	P5	P5	D3	C1	179
I/O, TDI	P6	P6	E4	D4	182
I/O, TCK	P7	P7	C1	D3	185
I/O	-	-	-	D2	188
I/O	-	-	-	D1	191
I/O	P8	P8	D1	E2	194
I/O	P9	P9	E3	E4	197
I/O	P10	P10	E2	E1	200
I/O	P11	P11	E1	F5	203
I/O	P12	P12	F3	F3	206
I/O	-	P13	F2	F2	209
GND	P13	P14	GND ⁽⁴⁾	GND ⁽⁴⁾	-
I/O	P14	P15	G3	F4	212
I/O	P15	P16	G2	F1	215
I/O, TMS	P16	P17	G1	G3	218
I/O	P17	P18	H3	G2	221
VCC	P18	P19	VCC ⁽⁴⁾	VCC ⁽⁴⁾	-
I/O	-	P20	H2	G4	224
I/O	-	P21	H1	H1	227
I/O	-	-	J4	H3	230
I/O	-	-	J3	H2	233
I/O	P19	P23	J2	H4	236
I/O	P20	P24	J1	J1	239
I/O	P21	P25	K2	J2	242
I/O	P22	P26	K3	J3	245
I/O	P23	P27	K1	J4	248
I/O	P24	P28	L1	K1	251

XCS40 and XCS40XL Device Pinouts

XCS40/XL Pad Name	PQ208	PQ240	BG256	CS280 ^(2,5)	Bndry Scan
GND	P25	P29	GND ⁽⁴⁾	GND ⁽⁴⁾	-
VCC	P26	P30	VCC ⁽⁴⁾	VCC ⁽⁴⁾	-
I/O	P27	P31	L2	K3	254
I/O	P28	P32	L3	K4	257
I/O	P29	P33	L4	K5	260
I/O	P30	P34	M1	L1	263
I/O	P31	P35	M2	L2	266
I/O	P32	P36	M3	L3	269
I/O	-	-	M4	L4	272
I/O	-	-	-	M1	275
I/O	-	P38	N1	M2	278
I/O	-	P39	N2	M3	281
VCC	P33	P40	VCC ⁽⁴⁾	VCC ⁽⁴⁾	-
I/O	P34	P41	P1	N1	284
I/O	P35	P42	P2	N2	287
I/O	P36	P43	R1	N3	290
I/O	P37	P44	P3	N4	293
GND	P38	P45	GND ⁽⁴⁾	GND ⁽⁴⁾	-
I/O	-	P46	T1	P1	296
I/O	P39	P47	R3	P2	299
I/O	P40	P48	T2	P3	302
I/O	P41	P49	U1	P4	305
I/O	P42	P50	T3	P5	308
I/O	P43	P51	U2	R1	311
I/O	-	-	-	R2	314
I/O	-	-	-	R4	317
I/O	P44	P52	V1	T1	320
I/O	P45	P53	T4	T2	323
I/O	P46	P54	U3	T3	326
I/O	P47	P55	V2	U1	329
I/O	P48	P56	W1	V1	332
I/O, SGCK2 ⁽¹⁾ , GCK2 ⁽²⁾	P49	P57	V3	U2	335
Not Connected ⁽¹⁾ M1 ⁽²⁾	P50	P58	W2	V2	338
GND	P51	P59	GND ⁽⁴⁾	GND ⁽⁴⁾	-
MODE ⁽¹⁾ , M0 ⁽²⁾	P52	P60	Y1	W1	341
VCC	P53	P61	VCC ⁽⁴⁾	VCC ⁽⁴⁾	-
Not Connected ⁽¹⁾ PWRDWN ⁽²⁾	P54	P62	W3	V3	342 ⁽¹⁾
I/O, PGCK2 ⁽¹⁾ , GCK3 ⁽²⁾	P55	P63	Y2	W2	343 ⁽³⁾

XCS40 and XCS40XL Device Pinouts

XCS40/XL Pad Name	PQ208	PQ240	BG256	CS280 ^(2,5)	Bndry Scan
I/O (HDC)	P56	P64	W4	W3	346 ⁽³⁾
I/O	P57	P65	V4	T4	349 ⁽³⁾
I/O	P58	P66	U5	U4	352 ⁽³⁾
I/O	P59	P67	Y3	V4	355 ⁽³⁾
I/O (LDC)	P60	P68	Y4	W4	358 ⁽³⁾
I/O	-	-	-	R5	361 ⁽³⁾
I/O	-	-	-	U5	364 ⁽³⁾
I/O	P61	P69	V5	T5	367 ⁽³⁾
I/O	P62	P70	W5	W5	370 ⁽³⁾
I/O	P63	P71	Y5	R6	373 ⁽³⁾
I/O	P64	P72	V6	U6	376 ⁽³⁾
I/O	P65	P73	W6	V6	379 ⁽³⁾
I/O	-	P74	Y6	T6	382 ⁽³⁾
GND	P66	P75	GND ⁽⁴⁾	GND ⁽⁴⁾	-
I/O	P67	P76	W7	W6	385 ⁽³⁾
I/O	P68	P77	Y7	U7	388 ⁽³⁾
I/O	P69	P78	V8	V7	391 ⁽³⁾
I/O	P70	P79	W8	W7	394 ⁽³⁾
VCC	P71	P80	VCC ⁽⁴⁾	VCC ⁽⁴⁾	-
I/O	P72	P81	Y8	W8	397 ⁽³⁾
I/O	P73	P82	U9	U8	400 ⁽³⁾
I/O	-	-	V9	V8	403 ⁽³⁾
I/O	-	-	W9	T8	406 ⁽³⁾
I/O	-	P84	Y9	W9	409 ⁽³⁾
I/O	-	P85	W10	V9	412 ⁽³⁾
I/O	P74	P86	V10	U9	415 ⁽³⁾
I/O	P75	P87	Y10	T9	418 ⁽³⁾
I/O	P76	P88	Y11	W10	421 ⁽³⁾
I/O (INIT)	P77	P89	W11	V10	424 ⁽³⁾
VCC	P78	P90	VCC ⁽⁴⁾	VCC ⁽⁴⁾	VCC ⁽⁴⁾
GND	P79	P91	GND ⁽⁴⁾	GND ⁽⁴⁾	-
I/O	P80	P92	V11	T10	427 ⁽³⁾
I/O	P81	P93	U11	R10	430 ⁽³⁾
I/O	P82	P94	Y12	W11	433 ⁽³⁾
I/O	P83	P95	W12	V11	436 ⁽³⁾
I/O	P84	P96	V12	U11	439 ⁽³⁾
I/O	P85	P97	U12	T11	442 ⁽³⁾
I/O	-	-	Y13	W12	445 ⁽³⁾
I/O	-	-	W13	V12	448 ⁽³⁾
I/O	-	P99	V13	U12	451 ⁽³⁾
I/O	-	P100	Y14	T12	454 ⁽³⁾
VCC	P86	P101	VCC ⁽⁴⁾	VCC ⁽⁴⁾	-
I/O	P87	P102	Y15	V13	457 ⁽³⁾
I/O	P88	P103	V14	U13	460 ⁽³⁾
I/O	P89	P104	W15	T13	463 ⁽³⁾

Product Availability

Table 19 shows the packages and speed grades for Spartan/XL devices. Table 20 shows the number of user I/Os available for each device/package combination.

Table 19: Component Availability Chart for Spartan/XL FPGAs

Device	Pins	84	100	144	144	208	240	256	280
	Type	Plastic PLCC	Plastic VQFP	Chip Scale	Plastic TQFP	Plastic PQFP	Plastic PQFP	Plastic BGA	Chip Scale
	Code	PC84 ⁽³⁾	VQ100 ⁽³⁾	CS144 ⁽³⁾	TQ144	PQ208	PQ240	BG256 ⁽³⁾	CS280 ⁽³⁾
XCS05	-3	C ⁽³⁾	C, I	-	-	-	-	-	-
	-4	C ⁽³⁾	C	-	-	-	-	-	-
XCS10	-3	C ⁽³⁾	C, I	-	C	-	-	-	-
	-4	C ⁽³⁾	C	-	C	-	-	-	-
XCS20	-3	-	C	-	C, I	C, I	-	-	-
	-4	-	C	-	C	C	-	-	-
XCS30	-3	-	C ⁽³⁾	-	C, I	C, I	C	C ⁽³⁾	-
	-4	-	C ⁽³⁾	-	C	C	C	C ⁽³⁾	-
XCS40	-3	-	-	-	-	C, I	C	C	-
	-4	-	-	-	-	C	C	C	-
XCS05XL	-4	C ⁽³⁾	C, I	-	-	-	-	-	-
	-5	C ⁽³⁾	C	-	-	-	-	-	-
XCS10XL	-4	C ⁽³⁾	C, I	C ⁽³⁾	C	-	-	-	-
	-5	C ⁽³⁾	C	C ⁽³⁾	C	-	-	-	-
XCS20XL	-4	-	C, I	C ⁽³⁾	C, I	C, I	-	-	-
	-5	-	C	C ⁽³⁾	C	C	-	-	-
XCS30XL	-4	-	C, I	-	C, I	C, I	C	C	C ⁽³⁾
	-5	-	C	-	C	C	C	C	C ⁽³⁾
XCS40XL	-4	-	-	-	-	C, I	C	C, I	C ⁽³⁾
	-5	-	-	-	-	C	C	C	C ⁽³⁾

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Notes:

1. C = Commercial $T_J = 0^\circ$ to $+85^\circ\text{C}$
2. I = Industrial $T_J = -40^\circ\text{C}$ to $+100^\circ\text{C}$
3. PC84, CS144, and CS280 packages, and VQ100 and BG256 packages for XCS30 only, discontinued by [PDN2004-01](#)
4. Some Spartan-XL devices are available in Pb-free package options. The Pb-free packages insert a "G" in the package code. Contact Xilinx for availability.

Package Specifications

Package drawings and material declaration data sheets for the Spartan/XL devices can be found on the Xilinx website at:

www.xilinx.com/support/documentation/spartan-xl.htm#19687

Thermal data for the Spartan/XL packages can be found using the thermal query tool on the Xilinx website at:

www.xilinx.com/cgi-bin/thermal/thermal.pl